

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A plasma processing reactor comprising:

a chamber having a removable substrate support asymmetric about a vertical axis of said chamber;

a RF power supply coupled to said chamber, said RF power supply adapted to supply RF power to said chamber to generate a plasma therein; and

an electrically resistive material selectively disposed on at least one of the substrate support or a surface of said chamber, the electrically resistive material having an RF impedance different from an underlying base material of said chamber.
2. (Previously Presented) The plasma processing reactor of claim 1, wherein said material includes varying composition to vary the RF impedance azimuthally.
3. (Previously Presented) The plasma processing reactor of claim 1, wherein said material has a selectively varying thickness to vary the RF impedance azimuthally.
4. (Previously Presented) The plasma processing reactor of claim 1, wherein said material is disposed in various shapes to vary the RF impedance azimuthally.

5. (Previously Presented) The plasma processing reactor of claim 1, wherein said material further comprises a plurality of film strips each having a variable thickness dimension.
6. (Previously Presented) The plasma processing reactor of claim 1, wherein said material further includes a plurality of film strips azimuthally positioned.
7. (Previously Presented) The plasma processing reactor of claim 1, wherein said material is selectively applied prior to processing a portion of a surface of said removable substrate support within said chamber.
8. (Previously Presented) The plasma processing reactor of claim 1, wherein said electrically resistive material includes Nickel.
9. (Previously Presented) The plasma processing reactor of claim 1, wherein said electrically resistive material includes Copper.
10. (Previously Presented) The plasma processing reactor of claim 1 wherein said material is plated to at least one of the substrate support or a surface of said chamber.
- 11-30. (Cancelled)